

HT9200A/HT9200B DTMF Generators

Features

- Operating voltage: 2.0V~5.5V
- Serial mode for the HT9200A
- Serial/parallel mode for the HT9200B
- · Low standby current

- · Low total harmonic distortion
- 3.58MHz crystal or ceramic resonator
- HT9200A: 8-pin DIP/SOP package HT9200B: 14-pin SOP package

General Description

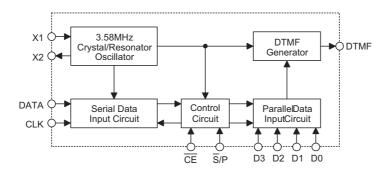
The HT9200A/B tone generators are designed for MCU interfaces. They can be instructed by a MCU to generate 16 dual tones and 8 single tones from the DTMF pin. The HT9200A provides a serial mode whereas the

HT9200B contains a selectable serial/parallel mode interface for various applications such as security systems, home automation, remote control through telephone lines, communication systems, etc.

Selection Table

Function Part No.	Operating Voltage	OSC Frequency	Interface	Package
HT9200A	2V~5.5V	3.58MHz	Serial	8 DIP/SOP
HT9200B	2V~5.5V	3.58MHz	Serial/Parallel	14 SOP

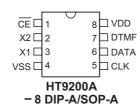
Block Diagram

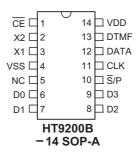


Rev. 1.41 1 February 23, 2009

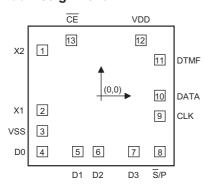


Pin Assignment





Pad Assignment



Pad Coordinates

Unit: µm

Pad No.	X	Υ	Pad No.	X	Y
1	-553.30	430.40	8	553.30	-523.50
2	-553.30	-133.50	9	553.30	-190.30
3	-553.30	-328.50	10	553.30	4.70
4	-553.30	-523.50	11	553.30	340.30
5	-220.10	-523.50	12	374.90	523.50
6	-25.10	-523.50	13	-279.30	523.50
7	308.10	-523.50			

Chip size: $1460\times1470~(\mu m)^2$

Pin Description

Pin Name	I/O	Internal Connection	Description
CE	ı	CMOS IN Pull-high	Chip enable, active low
X2	0		The system oscillator consists of an inverter, a bias resistor, and the required load
X1	I	Oscillator	capacitor on chip. The oscillator function can be implemented by Connect a standard 3.579545MHz crystal to the X1 and X2 terminals.
VSS	_	_	Negative power suppl, ground
NC	_	_	No connection
D0~D3	I	CMOS IN Pull-high or Floating	Data inputs for the parallel mode When the IC is operating in the serial mode, the data input terminals (D0~D3) are included with a pull-high resistor. When the IC is operating in the parallel mode, these pins become floating.
S/P	I	CMOS IN	Operation mode selection input S/P="H": Parallel mode S/P="L": Serial mode
CLK	I	CMOS IN Pull-high or Floating	Data synchronous clock input for the serial mode When the IC is operating in the parallel mode, the input terminal (CLK) is included with a pull-high resistor. When the IC is operating in the serial mode, this pin becomes floating.

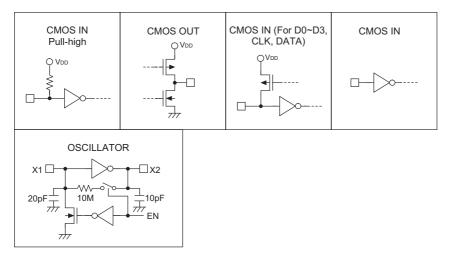
Rev. 1.41 2 February 23, 2009

^{*} The IC substrate should be connected to VSS in the PCB layout artwork.



Pin Name	I/O	Internal Connection	Description
DATA	ı	CMOS IN Pull-high or Floating	Data input terminal for the serial mode When the IC is operating in the parallel mode, the input terminal (DATA) is included with a pull-high resistor. When the IC is operating in the serial mode, this pin be- comes floating.
DTMF	0	CMOS OUT	Output terminal of the DTMF signal
VDD	_	_	Positive power supply, 2.0V~5.5V for normal operation

Approximate internal connection circuits



Absolute Maximum Ratings

Supply Voltage0.3V to 6V	Storage Temperature50°C to 125°C
Input VoltageV _{SS} -0.3 to V _{DD} +0.3V	Operating Temperature20°C to 75°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.



Electrical Characteristics

Ta=25°C

Tel:0755-82536500

Sumbol	Parameter		Test Conditions	Min.	Turn	Max.	Unit	
Symbol	Parameter	V_{DD}	Conditions	IVIIII.	Тур.	wax.	Unit	
V_{DD}	Operating Voltage	_	_	2	_	5.5	V	
1	On a setting at Command	2.5V	5V S/P=V _{DD} ,D0~D3=V _{SS} ,		240	2500	•	
I _{DD}	I _{DD} Operating Current		CE=V _{SS} , No load	_	950	3000	μА	
V_{IL}	"Low" Input Voltage	_	_	VSS	_	0.2V _{DD}	V	
V_{IH}	"High" Input Voltage	_	_	0.8V _{DD}	_	V _{DD}	V	
	Charadha Camant	2.5V	S/P=V _{DD} , CE=V _{DD} , no load	_	_	1		
I _{STB}	Standby Current	5.0V	3/F-VDD,CE-VDD, 110 10au	_	_	2	μΑ	
R₽	2.5V		V _{OL} =0V	120 180	180	270	10	
КР	Pull-high Resistance	5.0V	VOL-UV	45	68	100	kΩ	
t_{DE}	DTMF Output Delay Time (Parallel Mode)	5V	_	_	t _{UP} +6	t _{UP} +8	ms	
V_{TDC}	DTMF Output DC Level	2V~ 5.5V	DTMF Output	0.45V _{DD}	_	0.75V _{DD}	٧	
I _{TOL}	DTMF Sink Current	2.5V	V _{DTMF} =0.5V	-0.1	_	_	mA	
V_{TAC}	DTMF Output AC Level	2.5V	Row group, R_L =5k Ω	0.12	0.15	0.18	Vrms	
A _{CR}	Column Pre-emphasis	2.5V	Row group=0dB	1	2	3	dB	
R_L	DTMF Output Load	2.5V	$t_{HD} \le -23dB$	5	_	_	kΩ	
t _{HD}	Tone Signal Distortion	2.5V	R _L =5kΩ	_	-30	-23	dB	
f _{CLK}	Clock Input Rate (Serial Mode)	_	_	_	100	500	kHz	
t _{UP}	Oscillator Starting Time (When CE is low)	5.0V	The time from $\overline{\text{CE}}$ falling edge to normal oscillator operation		_	10	ms	
fosc	System Frequency	_	Crystal=3.5795MHz	3.5759	3.5795	3.5831	MHz	



Functional Description

The HT9200A/B are DTMF generators for MCU interfaces. They are controlled by a MCU in the serial mode or the parallel mode (for the HT9200B only).

Serial mode (HT9200A/B)

The HT9200A/B employ a data input, a 5-bit code, and a synchronous clock to transmit a DTMF signal. Every digit of a phone number to be transmitted is selected by a series of inputs which consist of 5-bit data. Of the 5

bits, the D0(LSB) is the first received bit. The HT9200A/B will latch data on the falling edge of the clock (CLK pin). The relationship between the digital codes and the tone output frequency is shown in Table 1. As for the control timing diagram, refer to Figure 1.

When the system is operating in the serial mode a pull-high resistor is attached to D0~D3 (for parallel mode) on the input terminal.

Table 1: Digits vs. input data vs. tone output frequency (serial mode)

Digit	D4	D3	D2	D1	D0	Tone Output Frequency (Hz)
1	0	0	0	0	1	697+1209
2	0	0	0	1	0	697+1336
3	0	0	0	1	1	697+1477
4	0	0	1	0	0	770+1209
5	0	0	1	0	1	770+1336
6	0	0	1	1	0	770+1477
7	0	0	1	1	1	852+1209
8	0	1	0	0	0	852+1336
9	0	1	0	0	1	852+1477
0	0	1	0	1	0	941+1336
*	0	1	0	1	1	941+1209
#	0	1	1	0	0	941+1477
A	0	1	1	0	1	697+1633
В	0	1	1	1	0	770+1633
С	0	1	1	1	1	852+1633
D	0	0	0	0	0	941+1633
_	1	0	0	0	0	697
_	1	0	0	0	1	770
_	1	0	0	1	0	852
_	1	0	0	1	1	941
_	1	0	1	0	0	1209
_	1	0	1	0	1	1336
_	1	0	1	1	0	1477
_	1	0	1	1	1	1633
DTMF OFF	1	1	1	1	1	

Note: The codes not listed in Table 1 are not used D4 is MSB



For the HT9200B, the \overline{S}/P pin has to be connected low for serial mode operation.

Parallel mode (HT9200B)

The HT9200B provides four data inputs D0~D3 to generate their corresponding DTMF signals. The \overline{S}/P has to be connected high to select the parallel operation mode. Then the input data codes should be determined. Finally, the \overline{CE} is connected low to transmit the DTMF signal from the DTMF pin.

The T_{DE} time (about 6ms) will be delayed from the \overline{CE} falling edge to the DTMF signal output.

The relationship between the digital codes and the tone output frequency is illustrated in Table 2. As for the control timing diagram, see Figure 2.

When the system is operating in the parallel mode, D0~D3 are all in the floating state. Thus, these data input pins should not float.

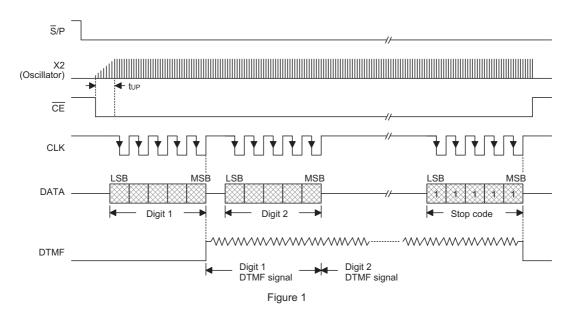
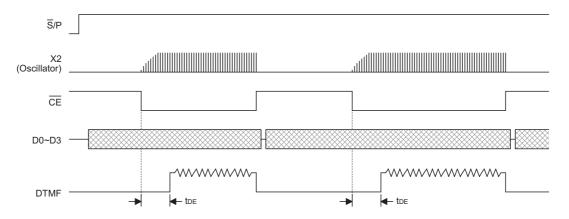


Table 2: Digits vs. input data vs. tone output frequency (parallel mode)

Digit	D3	D2	D1	D0	Tone Output Frequency (Hz)
1	0	0	0	1	697+1209
2	0	0	1	0	697+1336
3	0	0	1	1	697+1477
4	0	1	0	0	770+1209
5	0	1	0	1	770+1336
6	0	1	1	0	770+1477
7	0	1	1	1	852+1209
8	1	0	0	0	852+1336
9	1	0	0	1	852+1477
0	1	0	1	0	941+1336
*	1	0	1	1	941+1209
#	1	1	0	0	941+1477
Α	1	1	0	1	697+1633
В	1	1	1	0	770+1633
С	1	1	1	1	852+1633
D	0	0	0	0	941+1633

Rev. 1.41 6 February 23, 2009





Note: The data (D0~D3) should be ready before the CE becomes low.

Figure 2

Tone frequency

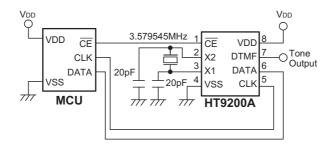
Output Fre	- %Error	
Specified	Actual	76EITOI
697	699	+0.29%
770	766	□0.52%
852	847	□0.59%
941	948	+0.74%
1209	1215	+0.50%
1336	1332	□0.30%
1477	1472	□0.34%

[%] Error does not contain the crystal frequency drift

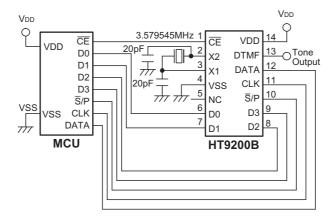


Application Circuits

Serial mode



Serial/parallel mode





Package Information

8-pin DIP (300mil) Outline Dimensions



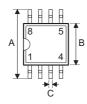




Combal	Dimensions in mil				
Symbol	Min.	Nom.	Max.		
А	355	_	375		
В	240	_	260		
С	125	_	135		
D	125	_	145		
E	16	_	20		
F	50	_	70		
G	_	100	_		
Н	295	_	315		
I	_	_	375		



8-pin SOP (150mil) Outline Dimensions





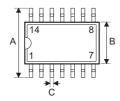


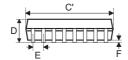
• MS-012

Comple al	Dimensions in mil				
Symbol	Min.	Nom.	Max.		
Α	228	_	244		
В	150	_	157		
С	12	_	20		
C'	188	_	197		
D	_	_	69		
E	_	50	_		
F	4	_	10		
G	16	_	50		
Н	7	_	10		
α	0°	_	8°		



14-pin SOP (150mil) Outline Dimensions







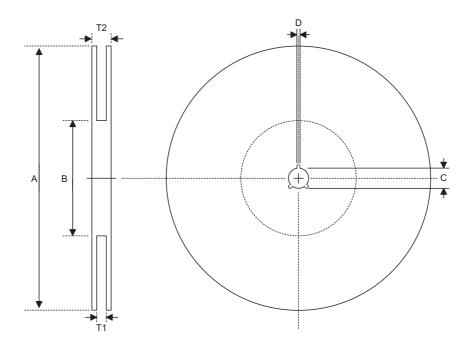
• MS-012

Symbol	Dimensions in mil				
Symbol	Min.	Nom.	Max.		
Α	228	_	244		
В	150		157		
С	12	_	20		
C'	337	_	344		
D	_	_	69		
E	_	50	_		
F	4	_	10		
G	16	_	50		
Н	7	_	10		
α	0°	_	8°		



Product Tape and Reel Specifications

Reel Dimensions



SOP 8N

Symbol	Description	Dimensions in mm
Α	Reel Outer Diameter	330.0±1.0
В	Reel Inner Diameter	100.0±1.5
С	Spindle Hole Diameter	13.0 +0.5/-0.2
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	12.8 +0.3/-0.2
T2	Reel Thickness	18.2±0.2

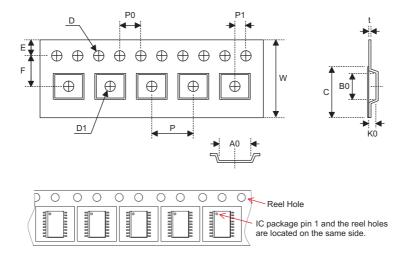
SOP 14N

Symbol	Description	Dimensions in mm
А	Reel Outer Diameter	330.0±1.0
В	Reel Inner Diameter	100.0±1.5
С	Spindle Hole Diameter	13.0 +0.5/-0.2
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	16.8 +0.3/-0.2
T2	Reel Thickness	22.2±0.2

Rev. 1.41 12 February 23, 2009



Carrier Tape Dimensions



SOP 8N

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	12.0 +0.3/-0.1
Р	Cavity Pitch	8.0±0.1
Е	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	5.5±0.1
D	Perforation Diameter	1.55±0.1
D1	Cavity Hole Diameter	1.50 +0.25/-0.00
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	6.4±0.1
В0	Cavity Width	5.2±0.1
K0	Cavity Depth	2.1±0.1
t	Carrier Tape Thickness	0.30±0.05
С	Cover Tape Width	9.3±0.1

SOP 14N

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	16.0 +0.3/-0.1
Р	Cavity Pitch	8.0±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	7.5±0.1
D	Perforation Diameter	1.5 +0.1/-0.0
D1	Cavity Hole Diameter	1.50 +0.25/-0.00
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	6.5±0.1
В0	Cavity Width	9.5±0.1
K0	Cavity Depth	2.1±0.1
t	Carrier Tape Thickness	0.30±0.05
С	Cover Tape Width	13.3±0.1

Rev. 1.41 13 February 23, 2009